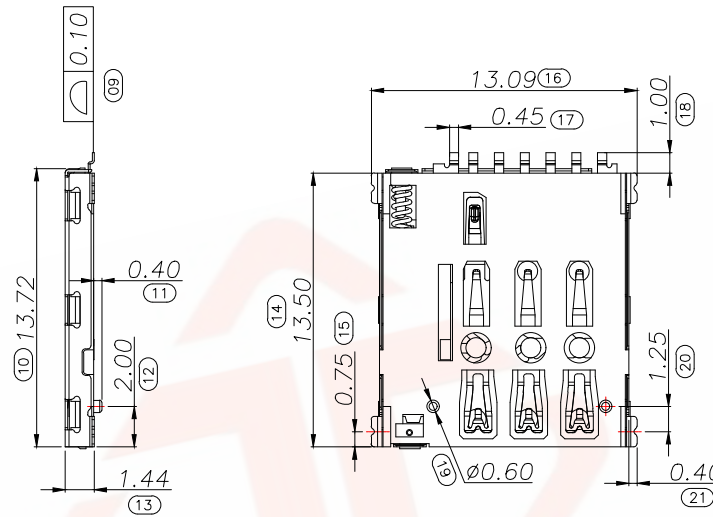
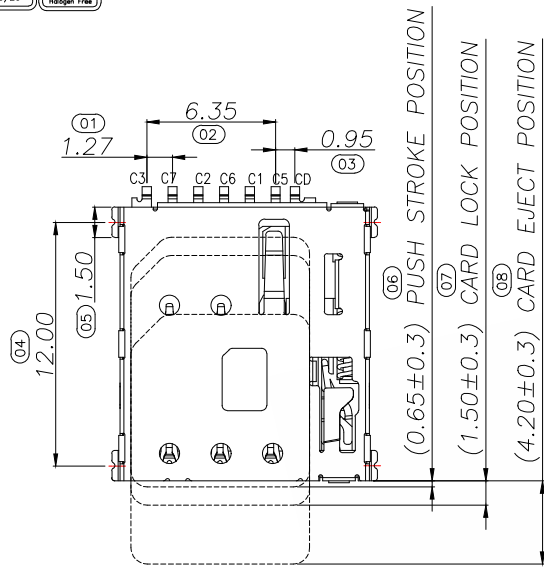
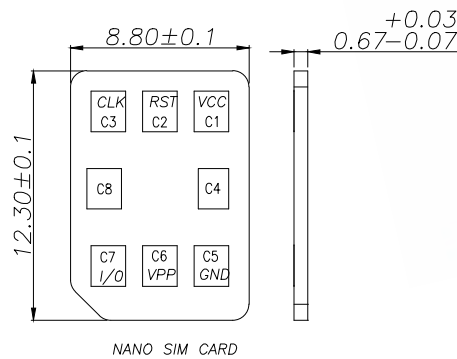
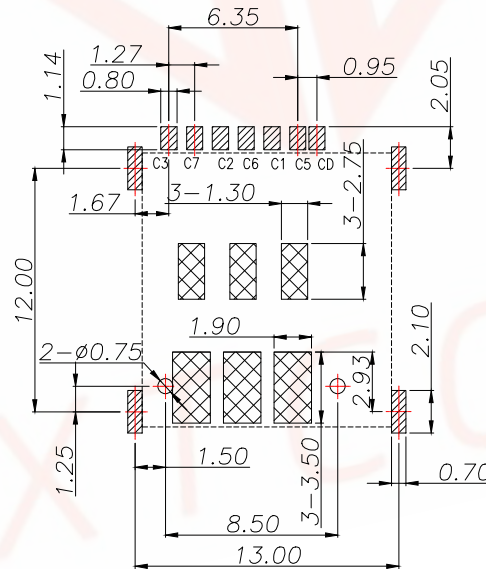
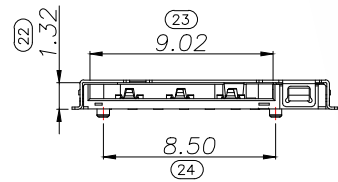


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



NOTES:

- 1) MATERIAL:
 - HOUSING: HI-TEMP. PLASIC UL 94V-0
 - CONTACT: COPPER ALLOY
 - SHELL: STAINLESS STEEL
- 2) PLATING:
 - TERMINAL:
 - CONTACT AREA: Au GOLD FLASH.
 - SOLDER AREA: AU GOLD FLASH.
 - UNDER PLATE: NICKEL.
 - SHELL: NICKEL PLATED OVER ALL.
 - SOLDER AREA: GOLD FLASH.
3. SPECIALITY:
 - 3.1 Rated current: 1.0A
 - 3.2 Rated voltage: 30V
 - 3.3 Contact Resistance: 50mΩ MAX
 - 3.4 Insulation Resistance: 1000MΩ MIN 500V DC
 - 3.5 Dielectric withstanding voltage: 500V AC.
 - 3.6 Solder ability: 260+0/-5℃, 30±10s.
 - 3.7 Durability: 5000 Cycles Min.
 - 3.8 Operating condition: Temperature -40℃~+85℃; Humidity 80% R.H MAX

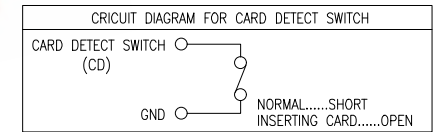


NANO SIM CARD

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

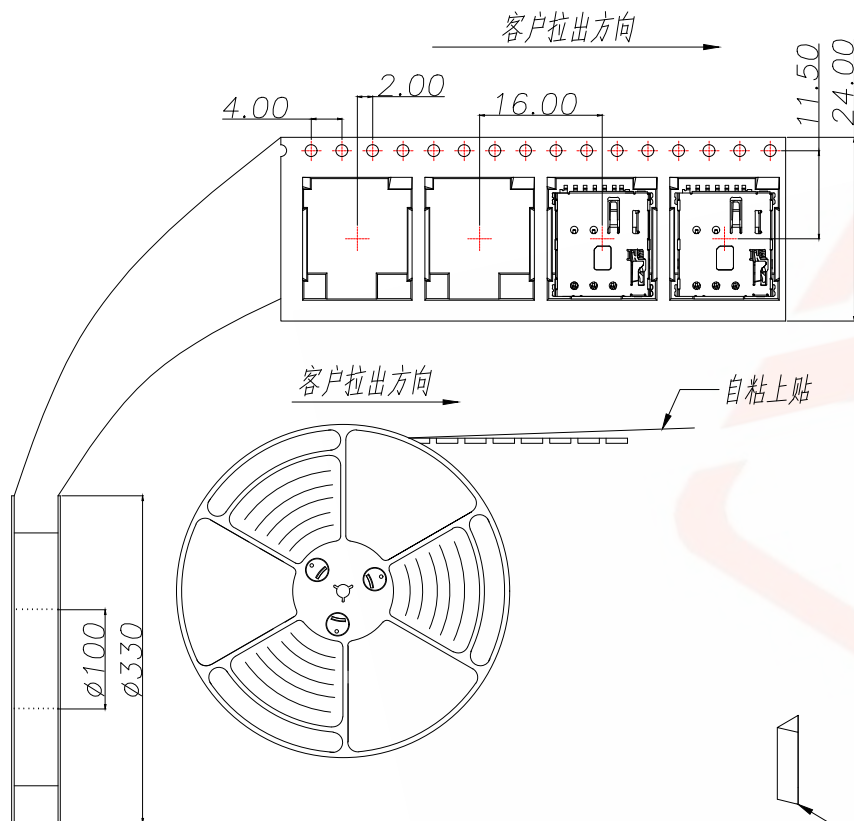
-  PAD
-  KEEP OUT AREA

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



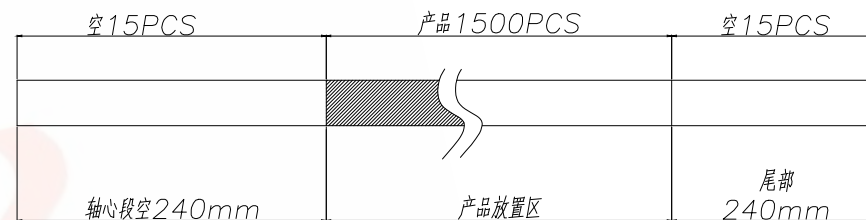
TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
X.: ±0.35	X': ±2'	PART NO.	TITLE: NANO SIM CARD
.X.: ±0.15	.X': ±1'	CSIM-113-7P	1.37H PUSH PUSH 有柱
.XX.: ±0.10	.XX': ±0.5'	DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olivia	 SCALE SHEET N:A 1/1
MATERILA	---	APPD: Ava	
FINISH	---		

REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

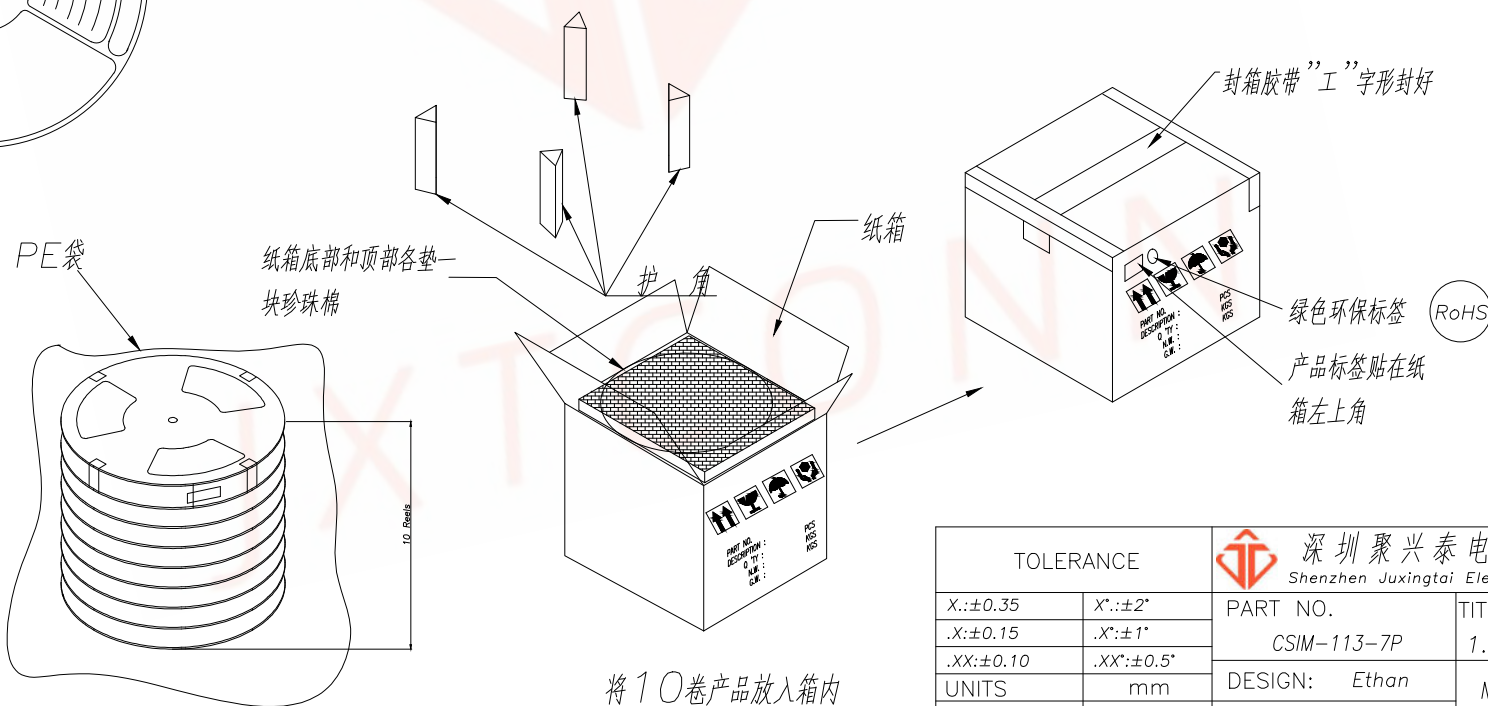


NOTES

1. 每卷包装数量: 1500PCS/每卷
2. 卷带包装方式:



3. 每箱包装数量: 15000PCS/箱
4. 纸箱350mm*350mm*340mm(内部尺寸), 材质K=K



将10卷产品放入箱内

TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
X.: ±0.35	X': ±2'	PART NO.	TITLE: NANO SIM CARD
.X.: ±0.15	.X': ±1'	CSIM-113-7P	1.37H PUSH PUSH 有柱
.XX.: ±0.10	.XX': ±0.5'	DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olivia	 SCALE SHEET N:A 1/1
MATERILA	---	APPD: Ava	
FINISH	---		